
Call for Papers — EMSOFT 2009

The 9th ACM International Conference on Embedded Software (EMSOFT)
October 12 to 16, 2009 – Grenoble, France
EMSOFT is a part of ESWEEK 2009 (<http://www.esweek.org/>)

Conference web site: <http://www.emsoft.org/>

EMSOFT is the annual ACM Conference on Embedded Systems Software sponsored by ACM SigBED (Special Interest Group on Embedded Systems). The purpose of this conference is to bring together researchers and developers from academia, industry, and government to advance the science, engineering, and technology in embedded software development.

EMSOFT was started in 2001. The previous editions of this conference were held in Lake Tahoe, USA (2001), Grenoble, France (2002), Philadelphia, USA (2003), Pisa, Italy (2004), Jersey City, USA (2005), Seoul, South Korea (2006), Salzburg, Austria (2007) and Atlanta, USA (2008).

From 2007 onwards, EMSOFT is being held as a part of the Embedded Systems Week (ESWeek), which contains three leading research conferences in embedded computing, all located at the same site: CASES, CODES+ISSS and EMSOFT. In addition, there are a number of workshops and tutorials affiliated with the main conferences.

CONFERENCE SCOPE:

Embedded software must meet demanding criteria for correctness, performance, power consumption, and development cost. EMSOFT aims at covering all aspects of embedded software with focus on principles of embedded software development. Topics of Interest include (but are not limited to):

- Design and implementation of embedded software
 - Modeling and validation
 - Model- and component-based software design and analysis
 - Programming languages and compilers
 - Software engineering and programming methodologies
 - Scheduling and execution time analysis
 - Operating systems and middleware
 - QoS management and performance analysis
 - Hardware-dependent software and interfaces
 - Networked embedded systems and security
 - Software for distributed/multiprocessor embedded systems
 - Application areas (automotive, avionics, communication/multimedia)
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PAPER SUBMISSIONS:

Submitted papers should present original research that is unpublished and not submitted elsewhere. Papers should be no more than 10 pages, 2-column in ACM format (templates are available from: <http://www.acm.org/sigs/publications/proceedings-templates>). The proceedings will be published by the Association for Computer Machinery (ACM).

A 300-word abstract should be submitted in plain text no later than May 1, 2009. The full paper should be submitted no later than May 8. The acceptable formats for the full paper are PDF and Postscript. PDF is preferred; if you wish to use Postscript, please ensure that all necessary fonts are embedded.

Prospective authors should submit both the abstract and the full papers via the submission page
<https://www.softconf.com/s08/emsoft2009>

This year authors will be allowed to see their reviews before the final decision, and their rebuttals will be taken into account while taking final acceptance/rejection decisions.

IMPORTANT DATES:

Abstract submission: Friday, May 1, 2009

Full paper submission: Friday, May 8, 2009

Rebuttal process: July 8-12, 2009

Acceptance notification: Friday, July 31, 2009

Final version submission: Sunday, August 9, 2009

Conference: October 12-16, 2009

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